

## Low power JFET single operational amplifiers

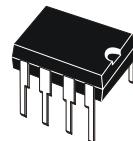
### Features

- Very low power consumption: 200  $\mu$ A
- Wide common-mode (up to  $V_{CC}^+$ ) and differential voltage ranges
- Low input bias and offset currents
- Output short-circuit protection
- High input impedance JFET input stage
- Internal frequency compensation
- Latch-up free operation
- High slew rate : 3.5V/ $\mu$ s

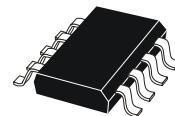
### Description

The TL061, TL061A and TL061B are high-speed JFET input single operational amplifiers. Each of these JFET input operational amplifiers incorporates well matched, high-voltage JFET and bipolar transistors in a monolithic integrated circuit.

The devices feature high slew rates, low input bias and offset currents, and low offset voltage temperature coefficient.

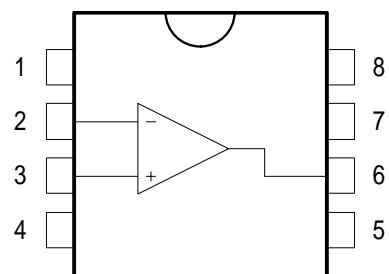


**N**  
**DIP8**  
(Plastic package)



**D**  
**SO-8**  
(Plastic micropackage)

### Pin connections (top view)



- 1 - Offset null 1
- 2 - Inverting input
- 3 - Non-inverting input
- 4 -  $V_{CC}^-$
- 5 - Offset null 2
- 6 - Output
- 7 -  $V_{CC}^+$
- 8 - N.C.

# 1 Schematic diagram

Figure 1. Schematic diagram

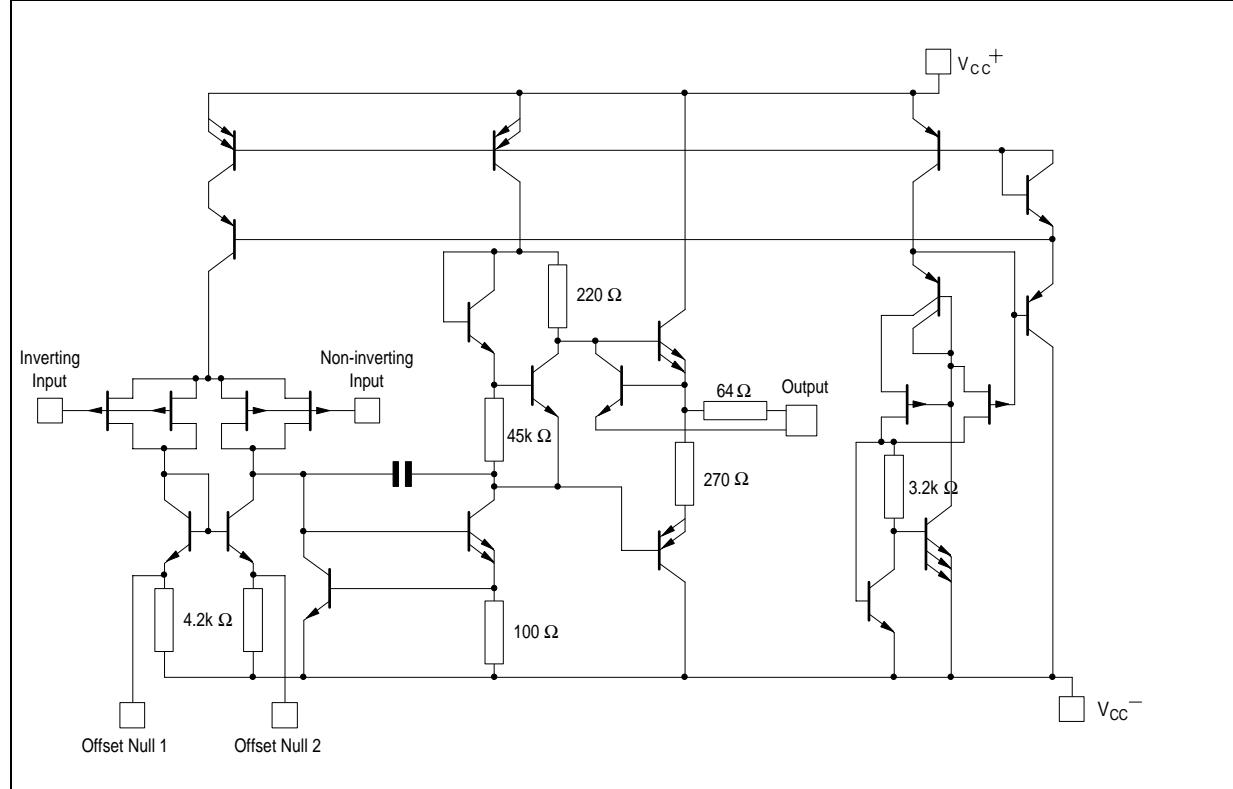
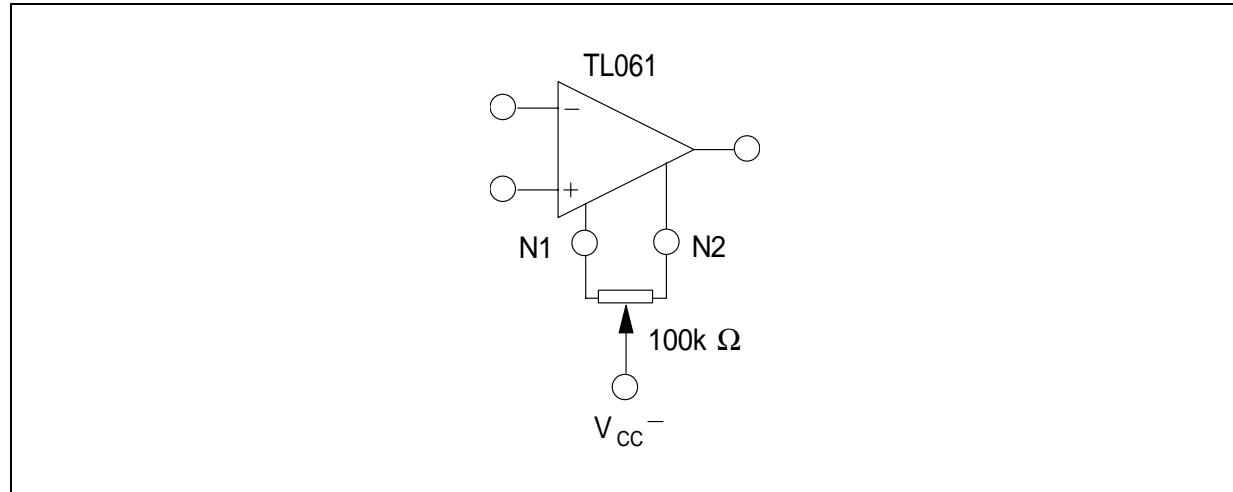


Figure 2. Input offset voltage null circuit



## 2 Absolute maximum ratings and operating conditions

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value			Unit
		TL061M, AM, BM	TL061I, AI, BI	TL061C, AC, BC	
V <sub>CC</sub>	Supply voltage <sup>(1)</sup>	±18			V
V <sub>i</sub>	Input voltage <sup>(2)</sup>	±15			V
V <sub>id</sub>	Differential input voltage <sup>(3)</sup>	±30			V
P <sub>tot</sub>	Power dissipation	680			mW
	Output short-circuit duration <sup>(4)</sup>	Infinite			
T <sub>stg</sub>	Storage temperature range	-65 to +150	-65 to +150	-65 to +150	°C
R <sub>thja</sub>	Thermal resistance junction to ambient <sup>(5) (6)</sup> SO-8 DIP8	125 85			°C/W
R <sub>thjc</sub>	Thermal resistance junction to case <sup>(5) (6)</sup> SO-8 DIP8	40 41			°C/W
ESD	HBM: human body model <sup>(7)</sup>	800			V
	MM: machine model <sup>(8)</sup>	200			V
	CDM: charged device model <sup>(9)</sup>	1.5			kV

1. All voltage values, except differential voltage, are with respect to the zero reference level (ground) of the supply voltages where the zero reference level is the midpoint between V<sub>CC</sub><sup>+</sup> and V<sub>CC</sub><sup>-</sup>.
2. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 volts, whichever is less.
3. Differential voltages are the non-inverting input terminal with respect to the inverting input terminal.
4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
5. Short-circuits can cause excessive heating and destructive dissipation.
6. R<sub>th</sub> are typical values.
7. Human body model: 100pF discharged through a 1.5kΩ resistor between two pins of the device, done for all couples of pin combinations with other pins floating.
8. Machine model: a 200pF cap is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5Ω), done for all couples of pin combinations with other pins floating.
9. Charged device model: all pins plus package are charged together to the specified voltage and then discharged directly to the ground.

**Table 2. Operating conditions**

Symbol	Parameter	TL061M, AM, BM	TL061I, AI, BI	TL061C, AC, BC	Unit
V <sub>CC</sub>	Supply voltage range	6 to 36			V
T <sub>oper</sub>	Operating free-air temperature range	-55 to +125	-40 to +105	0 to +70	°C

### 3 Electrical characteristics

**Table 3.**  $V_{CC} = \pm 15V$ ,  $T_{amb} = +25^{\circ}C$  (unless otherwise specified)

Symbol	Parameter	TL061M			TL061I			TL061C			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
$V_{io}$	Input offset voltage ( $R_S = 50\Omega$ $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$ )		3	6 9		3	6 9		3	15 20	mV
$DV_{io}$	Temperature coefficient of input offset voltage ( $R_S = 50\Omega$ )		10			10			10		$\mu V/^{\circ}C$
$I_{io}$	Input offset current <sup>(1)</sup> $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$		5	100 20		5	100 10		5	200 5	pA nA
$I_{ib}$	Input bias current <sup>(1)</sup> $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$		30	200 20		30	200 20		30	400 10	pA nA
$V_{icm}$	Input common mode voltage range	$\pm 11.5$	+15 -12		$\pm 11.5$	+15 -12		$\pm 11$	+15 -12		V
$V_{opp}$	Output voltage swing ( $R_L = 10k\Omega$ ) $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$	20 20	27		20 20	27		20 20	27		V
$A_{vd}$	Large signal voltage gain $R_L = 10k\Omega$ $V_o = \pm 10V$ , $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$	4 4	6		4 4	6		3 3	6		V/mV
GBP	Gain bandwidth product $T_{amb} = +25^{\circ}C$ , $R_L = 10k\Omega$ , $C_L = 100pF$		1			1			1		MHz
$R_i$	Input resistance		$10^{12}$			$10^{12}$			$10^{12}$		$\Omega$
CMR	Common mode rejection ratio $R_S = 50\Omega$	80	86		80	86		70	76		dB
SVR	Supply voltage rejection ratio $R_S = 50\Omega$	80	95		80	95		70	95		dB
$I_{cc}$	Supply current, no load $T_{amb} = +25^{\circ}C$ , no load, no signal		200	250		200	250		200	250	$\mu A$
$P_D$	Total power consumption $T_{amb} = +25^{\circ}C$ , no load, no signal		6	7.5		6	7.5		6	7.5	mW
SR	Slew rate $V_i = 10V$ , $R_L = 10k\Omega$ , $C_L = 100pF$ , $A_v = 1$	1.5	3.5		1.5	3.5		1.5	3.5		$V/\mu s$
$t_r$	Rise time $V_i = 20mV$ , $R_L = 10k\Omega$ , $C_L = 100pF$ , $A_v = 1$		0.2			0.2			0.2		$\mu s$

**Table 3.**  $V_{CC} = \pm 15V$ ,  $T_{amb} = +25^{\circ}C$  (unless otherwise specified) (continued)

Symbol	Parameter	TL061M			TL061I			TL061C			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
$K_{ov}$	Overshoot factor (see <i>Figure 16</i> ) $V_i = 20mV$ , $R_L = 10k\Omega$ , $C_L = 100pF$ , $A_V = 1$		10			10			10		%
$e_n$	Equivalent input noise voltage $R_S = 100\Omega$ , $f = 1kHz$		42			42			42		$\frac{nV}{\sqrt{Hz}}$

1. The input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

**Table 4.**  $V_{CC} = \pm 15V$ ,  $T_{amb} = +25^{\circ}C$  (unless otherwise specified)

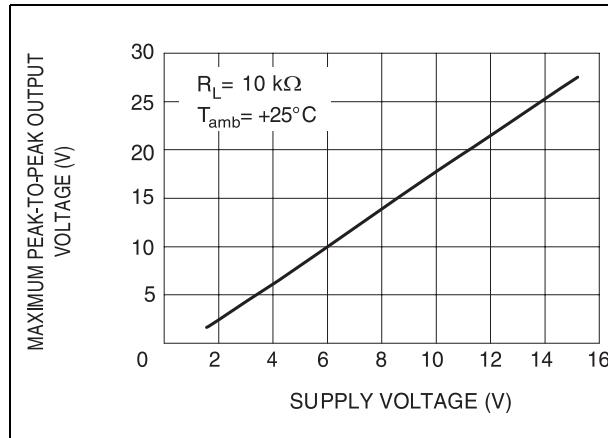
Symbol	Parameter	TL061AC, AI, AM			TL061BC, BI, BM			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
$V_{io}$	Input offset voltage ( $R_S = 50\Omega$ ) $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$		3	6 7.5		2	3 5	mV
$DV_{io}$	Temperature coefficient of input offset voltage ( $R_S = 50\Omega$ )		10			10		$\mu V/^{\circ}C$
$I_{io}$	Input offset current <sup>(1)</sup> $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$		5	100 3		5	100 3	pA nA
$I_{ib}$	Input bias current <sup>(1)</sup> $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$		30	200 7		30	200 7	pA nA
$V_{icm}$	Input common mode voltage range	$\pm 11.5$	+15 -12		$\pm 11$	+15 -12		V
$V_{opp}$	Output voltage swing ( $R_L = 10k\Omega$ ) $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$	20 20	27		20 20	27		V
$A_{vd}$	Large signal voltage gain ( $R_L = 10k\Omega$ , $V_o = \pm 10V$ ) $T_{amb} = +25^{\circ}C$ $T_{min} \leq T_{amb} \leq T_{max}$	4 4	6		4 4	6		V/mV
GBP	Gain bandwidth product $T_{amb} = +25^{\circ}C$ , $R_L = 10k\Omega$ , $C_L = 100pF$		1			1		MHz
$R_i$	Input resistance		$10^{12}$			$10^{12}$		$\Omega$
CMR	Common mode rejection ratio ( $R_S = 50\Omega$ )	80	86		80	86		dB
SVR	Supply voltage rejection ratio ( $R_S = 50\Omega$ )	80	95		80	95		dB
$I_{cc}$	Supply current, no load $T_{amb} = +25^{\circ}C$ , no load, no signal		200	250		200	250	$\mu A$
$P_D$	Total power consumption $T_{amb} = +25^{\circ}C$ , no load, no signal		6	7.5		6	7.5	mW

**Table 4.**  $V_{CC} = \pm 15V$ ,  $T_{amb} = +25^{\circ}C$  (unless otherwise specified) (continued)

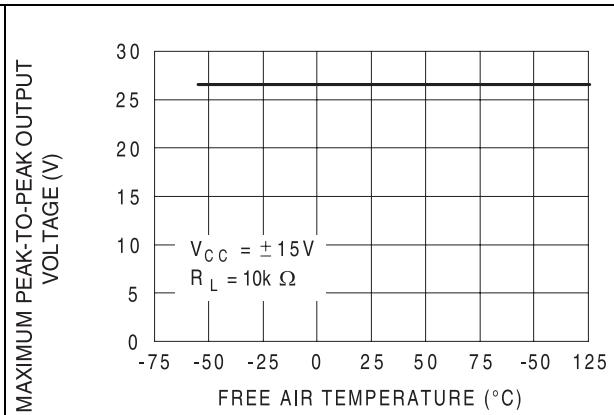
Symbol	Parameter	TL061AC, AI, AM			TL061BC, BI, BM			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
SR	Slew rate $V_i = 10V$ , $R_L = 10k\Omega$ , $C_L = 100pF$ , $A_v = 1$	1.5	3.5		1.5	3.5		V/ $\mu$ s
$t_r$	Rise time $V_i = 20mV$ , $R_L = 10k\Omega$ , $C_L = 100pF$ , $A_v = 1$		0.2			0.2		$\mu$ s
$K_{ov}$	Overshoot factor (see <i>Figure 16</i> ) $V_i = 20mV$ , $R_L = 10k\Omega$ , $C_L = 100pF$ , $A_v = 1$		10			10		%
$e_n$	Equivalent input noise voltage $R_S = 100\Omega$ , $f = 1KHz$		42			42		$\frac{nV}{\sqrt{Hz}}$

1. The input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible

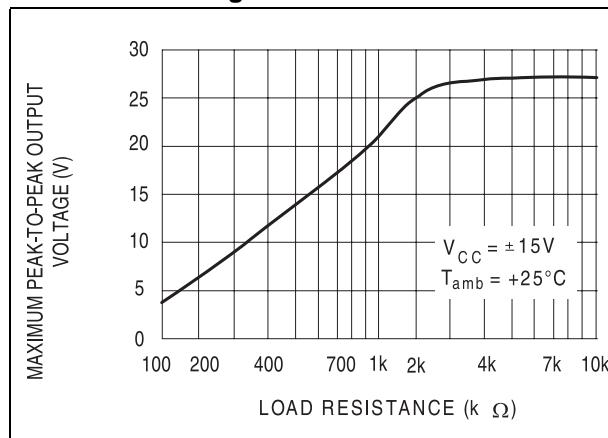
**Figure 3. Maximum peak-to-peak output voltage versus supply voltage**



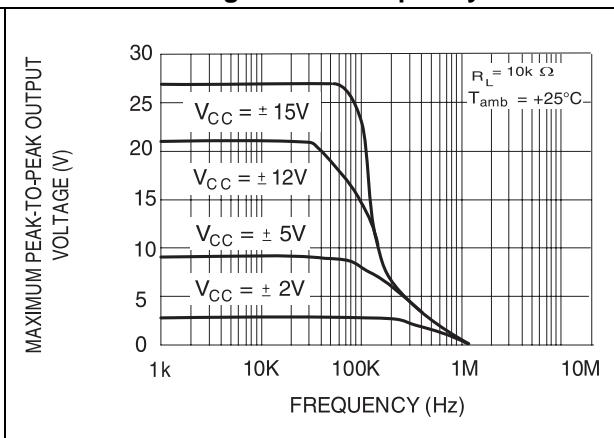
**Figure 4. Maximum peak-to-peak output voltage versus free air temperature**



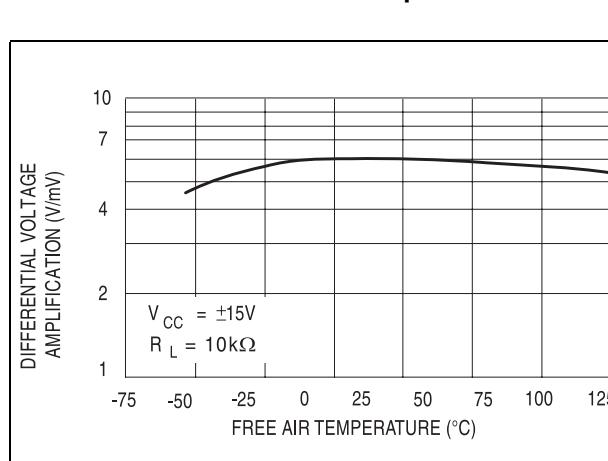
**Figure 5. Maximum peak-to-peak output voltage versus load resistance**



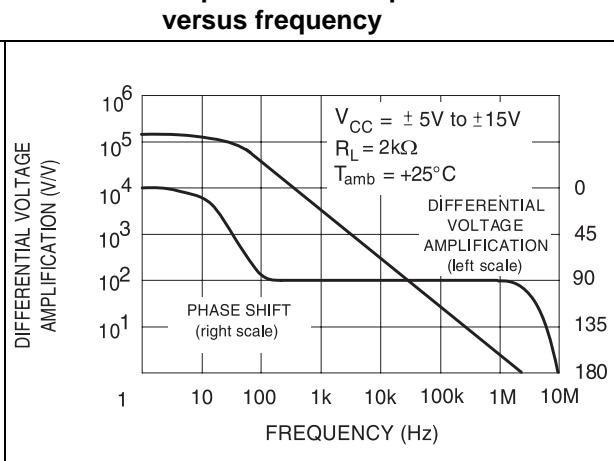
**Figure 6. Maximum peak-to-peak output voltage versus frequency**



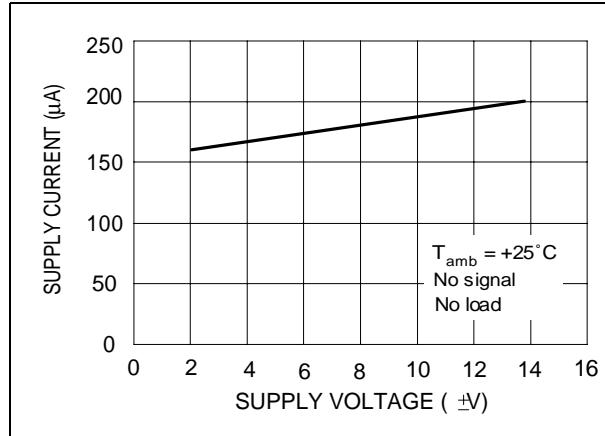
**Figure 7. Differential voltage amplification versus free air temperature**



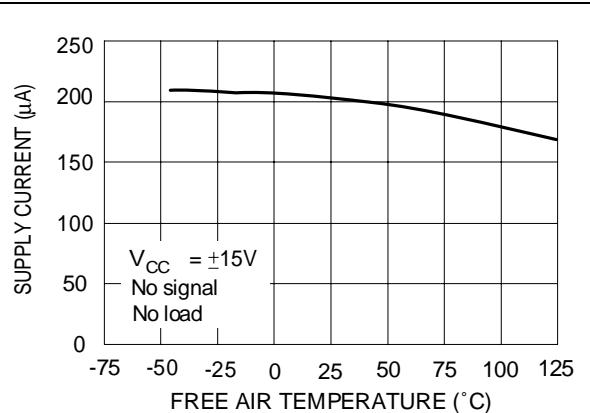
**Figure 8. Large signal differential voltage amplification and phase shift versus frequency**



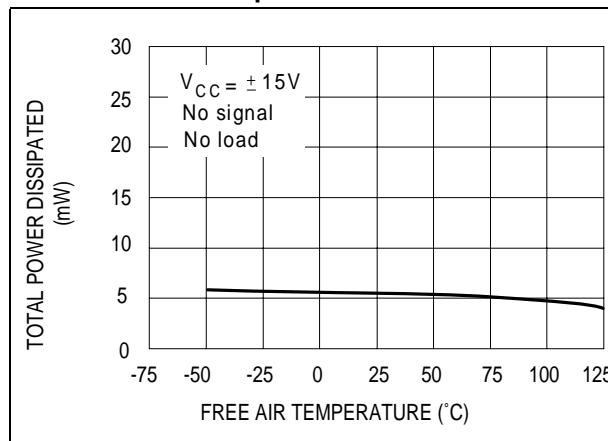
**Figure 9. Supply current per amplifier versus supply voltage**



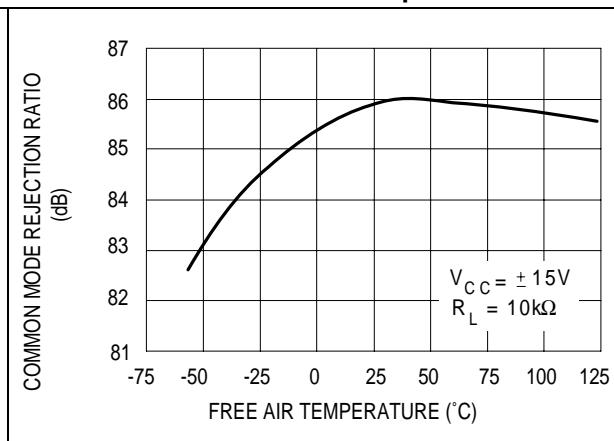
**Figure 10. Supply current per amplifier versus free air temperature**



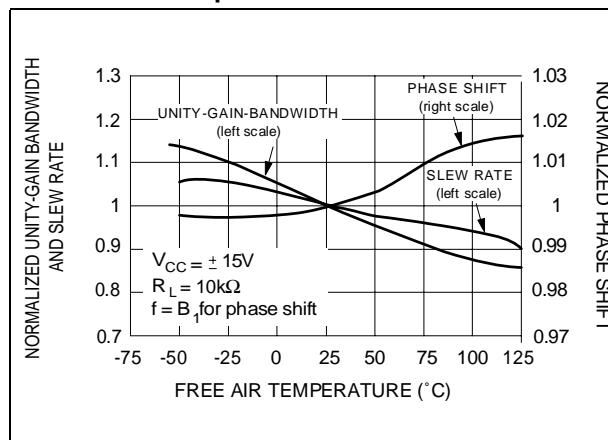
**Figure 11. Total power dissipated versus free air temperature**



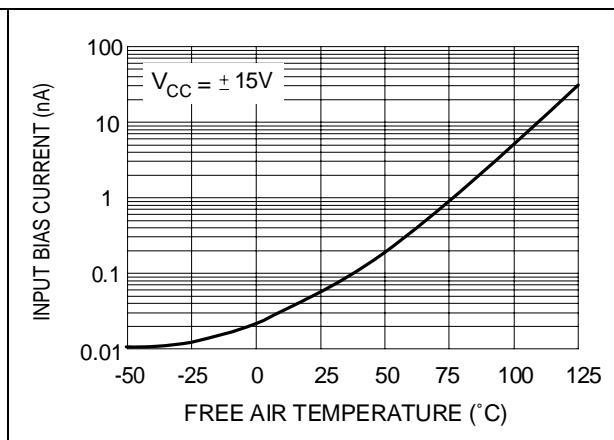
**Figure 12. Common mode rejection ratio versus free air temperature**



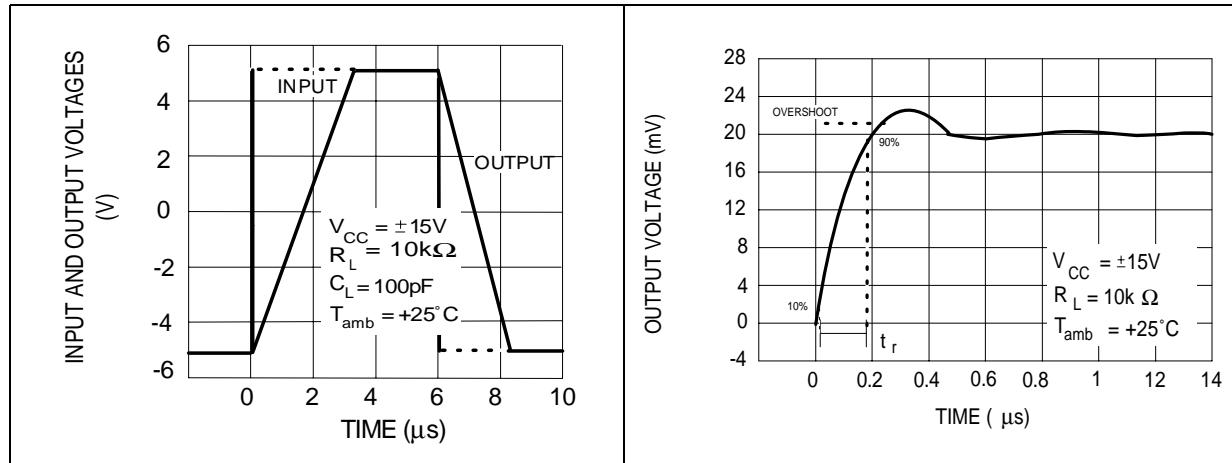
**Figure 13. Normalized unity gain bandwidth slew rate, and phase shift versus temperature**



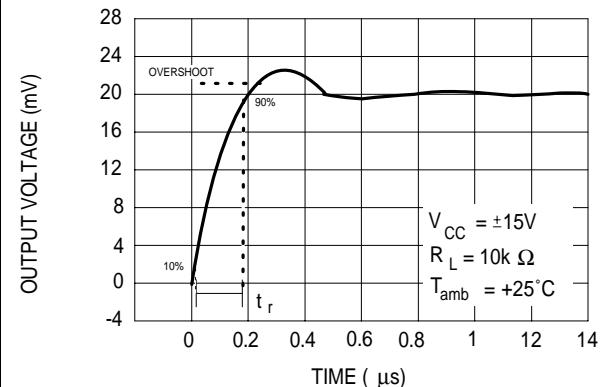
**Figure 14. Input bias current versus free air temperature**



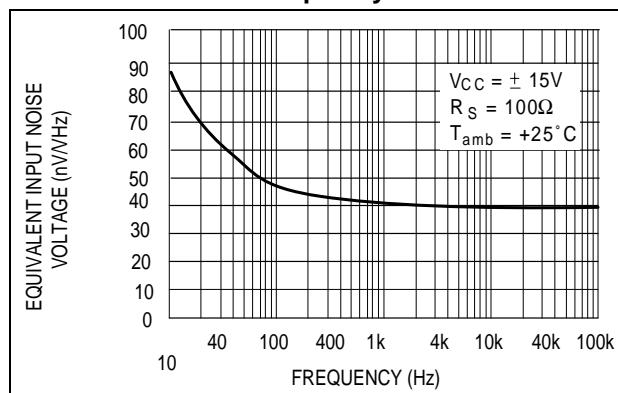
**Figure 15. Voltage follower large signal pulse response**



**Figure 16. Output voltage versus elapsed time**

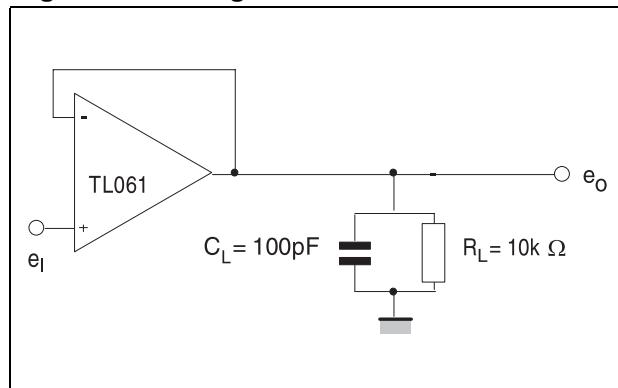


**Figure 17. Equivalent input noise voltage versus frequency**

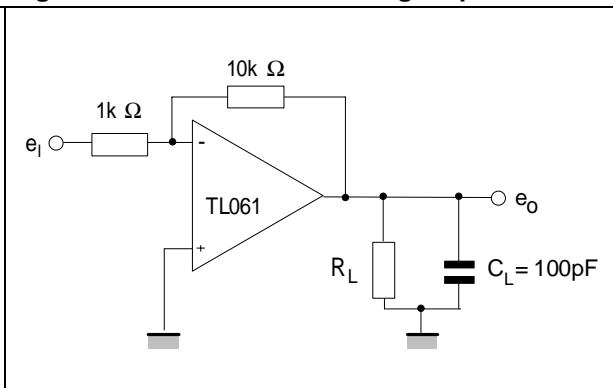


## Parameter measurement information

**Figure 18. Voltage follower**



**Figure 19. Gain-of-10 inverting amplifier**



## 4 Package information

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com).

Figure 20. DIP8 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			5.33			0.210
A1	0.38			0.015		
A2	2.92	3.30	4.95	0.115	0.130	0.195
b	0.36	0.46	0.56	0.014	0.018	0.022
b2	1.14	1.52	1.78	0.045	0.060	0.070
c	0.20	0.25	0.36	0.008	0.010	0.014
D	9.02	9.27	10.16	0.355	0.365	0.400
E	7.62	7.87	8.26	0.300	0.310	0.325
E1	6.10	6.35	7.11	0.240	0.250	0.280
e		2.54			0.100	
eA		7.62			0.300	
eB			10.92			0.430
L	2.92	3.30	3.81	0.115	0.130	0.150

The figure contains three technical drawings of a DIP8 package. The top drawing shows a top-down view with dimensions A, A1, A2, b, b2, c, D, E, E1, e, eA, eB, and L. The middle drawing shows a side view with dimensions E, c, eA, eB, and H. The bottom drawing shows a cross-sectional view with a dimension of 0.38 labeled 'GAUGE PLANE 0.38'.

Figure 21. SO-8 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.069
A1	0.10		0.25	0.004		0.010
A2	1.25			0.049		
b	0.28		0.48	0.011		0.019
c	0.17		0.23	0.007		0.010
D	4.80	4.90	5.00	0.189	0.193	0.197
H	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e		1.27			0.050	
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	1°		8°	1°		8°
ccc			0.10			0.004

The diagram illustrates the mechanical dimensions of the SO-8 package. It includes a top view showing lead spacing (e), lead height (h), and body width (D). A side view shows lead thickness (A), lead pitch (A1), lead height (A2), and lead width (b). A cross-sectional view shows the seating plane (C), gage plane (0.25 mm), lead length (L), and lead width (L1). The package is shown with pins numbered 1 through 8.

## 5 Ordering information

**Table 5. Order codes**

Part number	Temperature range	Package	Packing	Marking
TL061MN TL061AMN TL061BMN	-55°C, +125°C	DIP8	Tube	TL061MN TL061AMN TL061BMN
TL061MD/MDT TL061AMD/AMDT TL061BMD/BMDT		SO-8	Tube or tape & reel	061M 061AM 061BM
TL061IN TL061AIN TL061BIN	-40°C, +105°C	DIP8	Tube	TL061IN TL061AIN TL061BIN
TL061ID>IDT TL061AID/AIDT TL061BID/BIDT		SO-8	Tube or tape & reel	061I 061AI 061BI
TL061CN TL061ACN TL061BCN	0°C, +70°C	DIP8	Tube	TL061CN TL061ACN TL061BCN
TL061CD/CDT TL061ACD/ACDT TL061BCD/BCDT		SO-8	Tube or tape & reel	061C 061AC 061BC

## 6 Revision history

**Table 6. Document revision history**

Date	Revision	Changes
13-Nov-2001	1	Initial release.
27-Jul-2007	2	Added values for $R_{thja}$ and $R_{thjc}$ in <a href="#">Table 1: Absolute maximum ratings</a> . Added <a href="#">Table 2: Operating conditions</a> . Updated format.

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